

ABSTRACT

A semiconductor package includes an interposer, a redistribution layer chip adjacent to the interposer, and a semiconductor element that overlaps the interposer and the redistribution layer chip. The redistribution layer chip includes a redistribution element that has a surface overlapping the semiconductor element and a first mold resin layer that is mounted to an opposite surface of the redistribution element and that contains resin. The opposite surface is opposite the surface of the redistribution element overlapping the semiconductor element. The redistribution element includes an insulating layer that has an insulation property and a first redistribution layer that is covered by the insulating layer. The first redistribution layer includes a first conductive portion that is at least partly located on the surface of the redistribution element overlapping the semiconductor element. The interposer includes a second redistribution layer that includes a second conductive portion that is located on a surface of the interposer overlapping the semiconductor element. The semiconductor element is electrically connected to the first conductive portion and the second conductive portion.